

L Number	Hits	Search Text	DB	Time stamp
-	22	(device mounting).ti. and (oohata).in.	USPAT; US-PGPUB	2003/04/18 13:34
-	20	"5783856"	USPAT; US-PGPUB	2003/05/01 17:28
-	1	5824186.pn.	USPAT; US-PGPUB	2003/05/01 17:29
-	4	"5617385"	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/01 17:30
-	1	56?17385	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/01 17:31
-	2	4465543.pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/01 17:47
-	1	4465543.URPN.	USPAT	2003/05/01 17:32
-	10040	mount\$3 and transfer\$4 and separat\$3 and wafer and plurality	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/01 17:49
-	4400	(mount\$3 and transfer\$4 and separat\$3 and wafer and plurality) and array\$3	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/01 17:49
-	2991	((mount\$3 and transfer\$4 and separat\$3 and wafer and plurality) and array\$3) and device and (multipl\$3 magnif\$6)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/01 17:50
-	128	29/\$.ccls. and ((mount\$3 and transfer\$4 and separat\$3 and wafer and plurality) and array\$3) and device and (multipl\$3 magnif\$6))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/01 18:05
-	512	29/418,759,760,832,834,836,840.ccls. and transfer\$4 and mount\$3 same board	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/01 18:57
-	148	(29/418,759,760,832,834,836,840.ccls. and transfer\$4 and mount\$3 same board) and repeat\$3	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/01 18:08
-	128	((29/418,759,760,832,834,836,840.ccls. and transfer\$4 and mount\$3 same board) and repeat\$3) and surface	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/01 18:08
-	111	((29/418,759,760,832,834,836,840.ccls. and transfer\$4 and mount\$3 same board) and repeat\$3) and surface) and device	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/01 18:31
-	8	5297333.URPN.	USPAT	2003/05/01 18:19
-	12	(29/418,759,760,832,834,836,840.ccls. and transfer\$4 and mount\$3 same board) and device and wafer and plurality and interval	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/01 18:54
-	11	("3708372" "3715258" "3743558" "3785903" "3894633" "4021292" "4029536" "4061521" "4142662" "4239576" "4291867").PN.	USPAT	2003/05/01 18:35
-	12	4239576.URPN.	USPAT	2003/05/01 18:36
-	12	4061521.URPN.	USPAT	2003/05/01 18:38
-	15	4457718.URPN.	USPAT	2003/05/01 18:40

-	2	5950802.pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB USPAT	2003/05/01 18:54
-	6	("3542412" "4061528" "4425074" "4832180" "5177434" "5575376").PN.	USPAT; EPO; JPO; DERWENT; IBM_TDB USPAT	2003/05/01 18:55
-	124	269/\$_ccls. and (transfer\$4 relocat\$3) and mount\$3 and remov\$3 and wafer and device	USPAT; EPO; JPO; DERWENT; IBM_TDB USPAT	2003/05/01 19:07
-	8	3755048.URPN.	USPAT; EPO; JPO; DERWENT; IBM_TDB USPAT	2003/05/01 19:06
-	12	device adj1 transferring and plurality and scal\$3 and expan\$4 and wafer and mount\$3	USPAT; EPO; JPO; DERWENT; IBM_TDB USPAT	2003/05/01 19:11
-	168	device adj1 transferring and plurality and wafer and mount\$3	USPAT; EPO; JPO; DERWENT; IBM_TDB USPAT	2003/05/01 19:21
-	80	(transfer\$4).ti. and plurality and wafer and mount\$3 and display	USPAT; EPO; JPO; DERWENT; IBM_TDB USPAT	2003/05/01 19:22
-	64	("3448510" "3955190" "4024626" "4266223" "4321747" "4409724" "4582395" "4583122" "4600274" "4644338" "4653858" "4653862" "4654117" "4655551" "4655552" "4660935" "4662719" "4716403" "4727047" "4735495" "4740782" "4770498" "4774205" "4782340" "4808983" "4810637" "4814830" "4819038" "4838654" "4838657" "4846931" "4855255" "4859997" "4862153" "4863877" "4870475" "4878086" "4883561" "4930874" "4935792" "4952031" "4961629" "4980308" "5013138" "5020881" "5054887" "5056895" "5069534" "5073772" "5075674" "5076666" "5087113" "5095304" "5099345" "5115232" "5117298" "5124834" "5256562" "5258325" "5347154" "5572045" "5574292" "5646432" "5736768").PN.	USPAT; EPO; JPO; DERWENT; IBM_TDB USPAT	2003/05/01 19:29
-	79	4838654.URPN.	USPAT	2003/05/01 19:32

US 4894706 A	19900116	Three-dimensional packaging of semiconductor device chips	361/770	Sato, Yoshiyuki et al.
US 6528351 B1	20030304	Integrated package and methods for making same	438/118	Nathan, Richard J. et al.
US 5783856 A	19980721	Method for fabricating self-assembling microstructures	257/618	Smith, John Stephen et al.
US 5824186 A	19981020	Method and apparatus for fabricating self-assembling microstructures	438/597	Smith, John Stephen et al.
US 4465543 A	19840814	Apparatus and method for arranging semiconductor pellets	156/542	Sadamasa, Tetsuo et al.
US 5950304 A	19990914	Methods of making semiconductor chip assemblies	29/831	Khandros, Igor Y. et al.
US 5265792 A	19931130	Light source and technique for mounting light emitting diodes	228/6.2	Harrah, Shane et al.
US 5258325 A	19931102	Method for manufacturing a semiconductor device using a circuit transfer film	438/107	Spitzer, Mark B. et al.
US 5249358 A	19931005	Jet impingement plate and method of making	29/890.03	Tousignant, Lew A. et al.
US 5144747 A	19920908	Apparatus and method for positioning an integrated circuit chip within a multichip module	29/834	Eichelberger, Charles W.
US 6519838 B1	20030218	Component mounting apparatus	29/740	Okuda, Osamu et al.
US 6298547 B1	20011009	Apparatus for holding component, apparatus for mounting component, and method for mounting component	29/740	Okuda, Osamu et al.
US 6266873 B1	20010731	Method and apparatus for mounting electronic components	29/832	Kitamura, Naoyuki et al.
US 6209194 B1	20010403	Apparatus for loading and unloading semiconductor device packages using servo motors	29/739	Kang, Ju Il et al.
US 5951720 A	19990914	IC mounting/demounting system and mounting/demounting head therefor	29/25.01	Arakawa, Isao et al.
US 6332268 B1	20011225	Method and apparatus for packaging IC chip, and tape-shaped carrier to be used therefor	29/832	Imanishi, Makoto et al.
US 3894633 A	19750715	Method and apparatus for sorting articles	209/643	Egan, James J. et al.
US 5114308 A	19920519	Method of placing components on carriers and device for carrying out the method	414/799	Smolders, Jozef G. H. M. et al.
US 6416612 B1	20020709	Method of making a color display device	156/277	Lerner, Stanley I. et al.
US 6030481 A	20000229	Method and apparatus for manufacture of watch bearing sheets	156/265	Winter, Steve et al.
US 5725717 A	19980310	Application of rows of labels to a packaging film	156/299	Harte, James R. et al.
US 5622594 A	19970422	Apparatus for the manufacture of sheets bearing display samples	156/521	Lerner, Stanley et al.
US 5950802 A	19990914	IC package transfer and relocation mechanism	198/468.3	Kubota, Toshihiro
US 6543513 B1	20030408	Wafer table for die bonding apparatus	156/540	Lau, Siu Wing et al.
US 6204094 B1	20010320	Method and apparatus for populating an adhesive sheet with particles	438/120	Hotchkiss, Gregory B. et al.
US 6555408 B1	20030429	Methods for transferring elements from a template to a substrate	438/28	Jacobsen, Jeffrey Jay et al.
US 6414783 B2	20020702	Method of transferring semiconductors	359/291	Zavracky, Paul M. et al.
US 6027958 A	20000222	Transferred flexible integrated circuit	438/110	Vu, Duy-Phach et al.
US 5976953 A	19991102	Three dimensional processor using transferred thin film circuits	438/455	Zavracky, Paul M. et al.
US 4878086 A	19891031	Flat panel display device and manufacturing of the same	355/77	Ishihata, Junji et al.